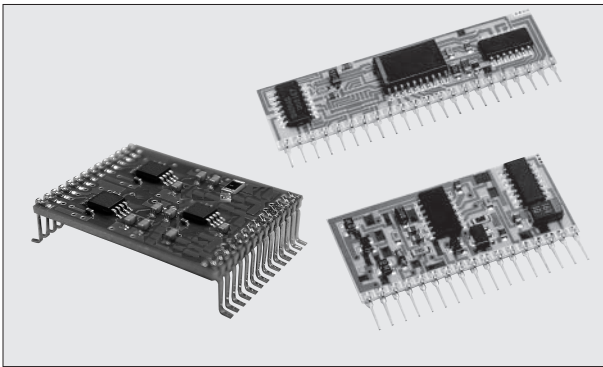


KA 定制混合IC Custom Hybrid IC



■ Applications

汽车设备 (ECU、电动方向盘)、电源设备 (DC/DC转换器AC/DC转换器、稳定电路、锂电池充放电电路)、工业设备 (各种控制电路)、通信设备 (电话交换机、LAN、无线收发器、VCO、VTXO)

Automotives applications (ECU, Power Windows), Power supply devices (DC/DC converters, AC/DC converters, Stabilizer, Lithium ion battery charger circuit)

Industry devices (control circuits), Telecommunication equipment (Telephone switchboard, LAN, Transceivers, VCO, VTXO)

■ 特点 Features

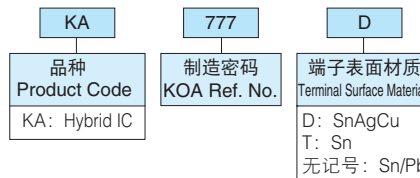
- 根据功能和比例的调整可以降低工时
- 由粘结的高密度实现(COB)。
- 各种包装对应可能。
- 由于使用KOA的厚膜技术使其信赖性向上。
- Adjustment processes are decreased by function and ratio trimmings.
- High density mounting by bonding (COB).
- Various types of package are available.
- High reliability achieved by KOA's original thick film technology.

■ 欧盟RoHS对应 EU-RoHS requirements

- 厚膜印刷基板，印刷电路板都进行各构成部件的优化内部连接实现了无铅化。
- Each constructional element of thick film printed circuit substrate and printed board has optimized material. Inner connecting solder is lead-free.

■ 品名构成 Type Designation

实例 Example



■ 构成零件 Component

KA Series				
	项目 Item	印刷 Printing	贴装 Mounting	粘合 Bonding
基板材料 Substrate Materials	Al ₂ O ₃ 氧化铝 Alumina	○	○	○
	玻璃环氧树脂 Glass epoxy	×	○	○
导体・电阻 Conductors・Resistors	项目 Item	Ag-Pd	Ag-Pt	
	导体电阻 Conductor resistance	18mΩ/□/15μm	5mΩ/□/10μm	
	热冲击 Heat shock	-55℃~+125℃ 300 Cycles	-55℃~+125℃ 500 Cycles	
	电阻体 RuO ₂	5Ω~10MΩ ±100×10 ⁻⁶ /K		
贴装 Mounting	项目 Item	规格 Specifications		
	COB	Au Wire, Al Wire		
	BGA	0.5mm Pitch~		
	QFP	0.4mm Pitch~		
	Chip	0.6mm×0.3mm (0.4mm×0.2mm) ~		
形状・外部端子 Package・Outside terminals	形状 Package	引线间距 Lead pitch		
	SIP	1.8mm, 2.0mm, 2.5mm, 2.54mm		
	DIP, SOP	1.27mm, 1.8mm, 2.54mm		
	ZIP	2.54mm		
	BGA, LGA	1.0mm~		
电镀・表面处理 Over coating・Plating	外装 Over Coating	色 Color	UL标准 UL Standard	
	环氧系变成苯酚 Epoxy metamorphic phenol	黑 Black	94 V0认定品 94 V0 approved	
	环氧树脂 Epoxy	黑 Black	94 V1认定品 94 V1 approved	